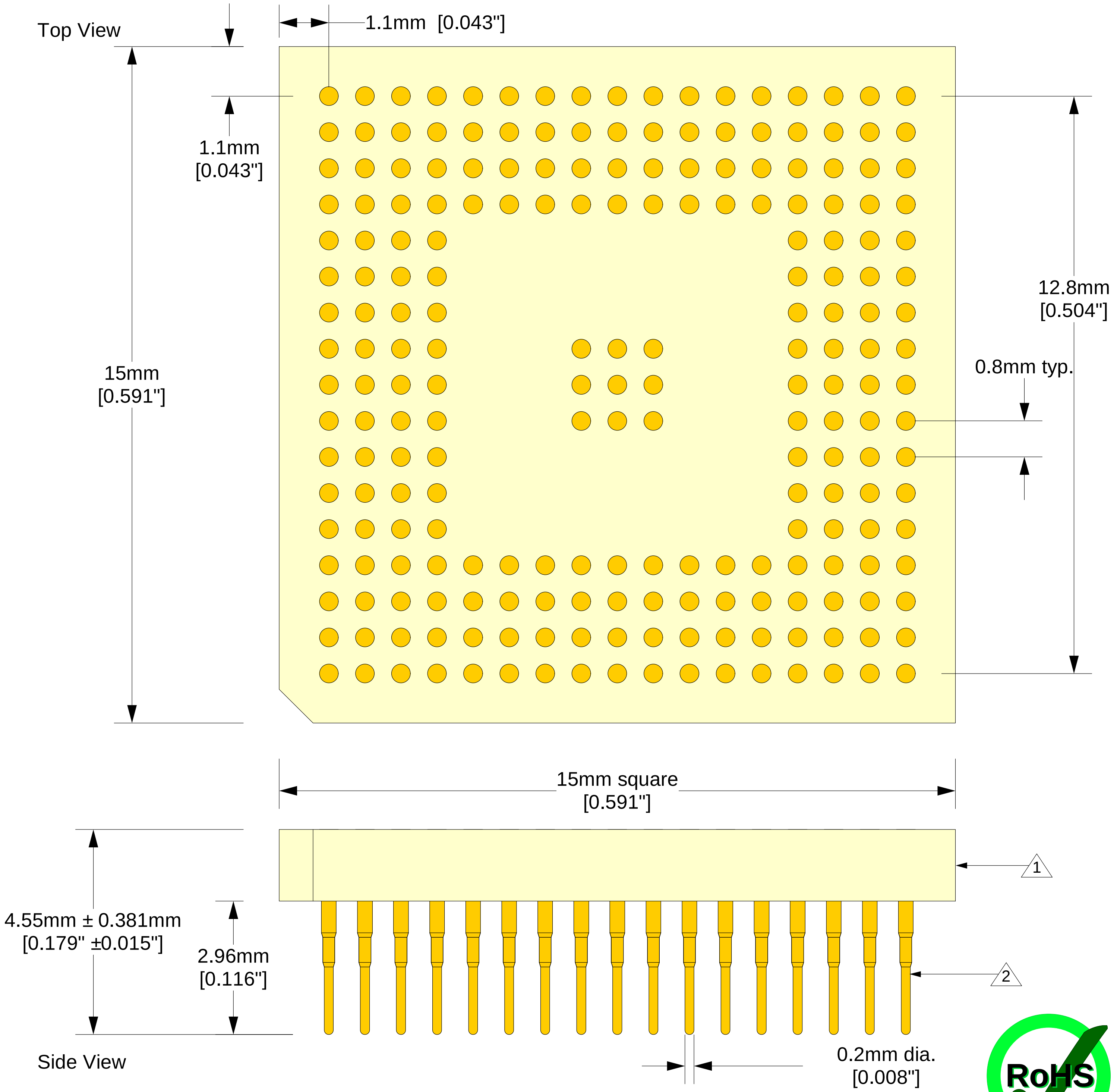

RoHS

1. Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. non clad
2. Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

<u>Description:</u> Giga-snaP BGA SMT Land Socket
217 position BGA surface mount land pattern to terminal pins (0.8mm centers, 17x17 array)

<u>Tolerances:</u> diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA217B-61 Drawing	Status: Released	Scale: 8:1	Rev: C
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 07/06/07	
	File: LS-BGA217B-61 Dwg.mcd	Modified: 01/18/13, DH	